



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Shuichi ICHIKAWA et al.

Group Art Unit: 2855

Application No.: 10/505,334

Examiner: G. VERBITSKY

Filed: August 23, 2004

Docket No.: 120868

For: METHOD OF MEASURING THERMAL CONDUCTIVITY OF HONEYCOMB
STRUCTURE

SUBMISSION OF REFERENCES UNDER 37 C.F.R. §1.97(i)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

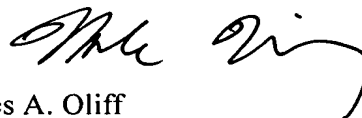
Sir:

In accordance with 37 C.F.R. §1.97(i) and MPEP 609.05(a), applicant requests that the attached reference be placed in the Patent Office files. The reference was cited in a Communication from the Japanese Patent Office.

- ☒ 1. One or more reference cited herein was cited in a counterpart foreign application. See Reference 2.
- ☒ 2. In accordance with 37 CFR §1.98(a)(2)(ii), copies of any U.S. patents and patent application publications are not attached.
- ☒ 3. An English language Abstract of one or more non-English language reference is attached. See Reference 2.

- ☒ 4. Reference 1 corresponds to reference 2.

Respectfully submitted,



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